

Product Change Notification - JAON-22LUWC382

Date: 09 May 2017

Product Category: KEELOQ® Encoder Devices; Interface- Passive-Keyless-Entry Analog Front End; Successive Approximation Register (SAR) A/D Converters; Digital Potentiometers; Linear Op Amps; Linear Comparators; 8-bit PIC Microcontrollers

Notification subject: CCB 1657 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 120K wafer technology available in 14L TSSOP package at MMT assembly site

Notification text: **PCN Status:**
Final notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 120K wafer technology available in 14L TSSOP package at MMT assembly site.

Pre Change:

Palladium coated copper wire (PdCu)

Post Change:

Palladium coated copper wire with gold flash (CuPdAu)

Impacts to Data Sheet:

None

Reason for Change:

To improve manufacturability and qualify palladium coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status:

In Progress

Estimated First Ship Date:

November 23, 2015 (date code: 1548)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Summary Table:

	July 2015	August 2015	September 2015	October 2015	November 2015
Initial PCN Issue Date	X				
Qual Report Availability				X	
Final PCN Issue Date				X	
Implementation Date					X

Markings to Distinguish Revised from Unrevised Devices:

Traceability code

Revision History:

July 07, 2015: Issued initial notification.

October 16, 2015: Issued final notification. Attached the qualification report. Revised the estimated first ship date

from October 20, 2015 to November 23, 2015.
May 09, 2017: Updated the affected CPN list.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s): [PCN_JAON-22LUWC382_Qual_Report1.pdf](#)
[PCN_JAON-22LUWC382_Affected_CPN1.pdf](#)
[PCN_JAON-22LUWC382_Affected_CPN1.xls](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PCN_JAON-22LUWC382
CATALOG_PART_NBR
HCS370/ST
HCS370-I/ST
HCS370T/ST
HCS370T-I/ST
MCP2030A-I/ST
MCP2030AT-I/ST
MCP2030-I/ST
MCP2030T-I/ST
MCP2035-I/ST
MCP2035T-I/ST
MCP3004-I/ST
MCP3004T-I/ST
MCP3204-BAI/ST
MCP3204-CI/ST
MCP3204T-BAI/ST
MCP3204T-CI/ST
MCP3302-BI/ST
MCP3302-CI/ST
MCP3302T-BI/ST
MCP3302T-CI/ST
MCP42010-E/ST
MCP42010-I/ST
MCP42010T-E/ST
MCP42010T-I/ST
MCP42050-E/ST
MCP42050-I/ST
MCP42050T-E/ST
MCP42050T-I/ST
MCP42100-E/ST
MCP42100-I/ST
MCP42100T-E/ST
MCP42100T-I/ST
MCP6004-E/ST
MCP6004-I/ST
MCP6004-I/STAAA
MCP6004T-E/ST
MCP6004T-I/ST
MCP6004T-I/STAAA
MCP6024-E/ST
MCP6024-I/ST
MCP6024T-E/ST
MCP6024T-I/ST
MCP6034-E/ST
MCP6034T-E/ST

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Affected Catalog Part Numbers (CPN)

PCN_JAON-22LUWC382
CATALOG_PART_NBR
MCP6044-E/ST
MCP6044-I/ST
MCP6044T-E/ST
MCP6044T-I/ST
MCP604-E/ST
MCP604-I/ST
MCP604-I/STAAA
MCP604T-E/ST
MCP604T-I/ST
MCP604T-I/STAAA
MCP6054-E/ST
MCP6054T-E/ST
MCP6064-E/ST
MCP6064T-E/ST
MCP6074-E/ST
MCP6074T-E/ST
MCP6234-E/ST
MCP6234T-E/ST
MCP6244-E/ST
MCP6244T-E/ST
MCP6274-E/ST
MCP6274T-E/ST
MCP6284-E/ST
MCP6284T-E/ST
MCP6294-E/ST
MCP6294T-E/ST
MCP6404-E/ST
MCP6404T-E/ST
MCP6444-E/ST
MCP6444T-E/ST
MCP6544-E/ST
MCP6544-I/ST
MCP6544T-E/ST
MCP6544T-I/ST
MCP6549-E/ST
MCP6549-I/ST
MCP6549T-E/ST
MCP6549T-I/ST
MCP6549T-I/STBAA
MCP6549T-I/STX
MCP6L04T-E/ST
MCP6L4T-E/ST
MCP6L74T-E/ST
MCP6L94T-E/ST

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Affected Catalog Part Numbers (CPN)

PCN_JAON-22LUWC382
CATALOG_PART_NBR
PIC16LC505-04/ST
PIC16LC505-04I/ST
MCP609-I/ST
MCP609T-I/ST